

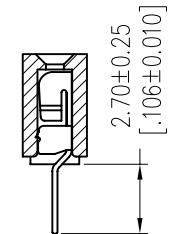
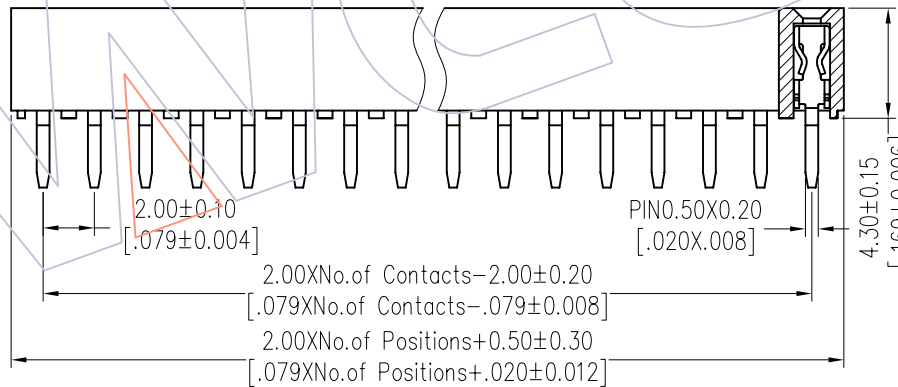
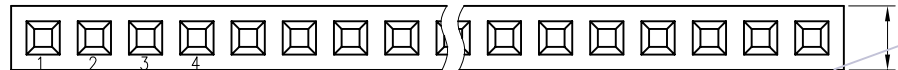
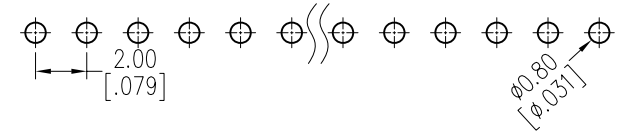
HSF

Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)

NOTES:

Current Rating: 2.0AMP
 Contact Resistance: 20mΩ Max
 Withstand Voltage: 500V AC/DC
 Insulation Resistance: 1000MΩ Min
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze
 Contact plating: Au Or Sn over Ni
 Insulator Material: PA9T+30%G.F UL94V-0



Ordering Information

2243-1 XX S XX CUN T 1

No. of Pins per Row: 02-40Pin

Contact Plating:
 G0=Gold Flash
 G3=10μ"Gold
 G4=15μ"Gold
 G5=30μ"Gold
 S0=Gold Flash/Tin
 S3=10μ"Gold/Tin
 S4=15μ"Gold/Tin
 S5=30μ"Gold/Tin
 SN=Tin
 SM=Matte Tin

Packing:
 T=Tube

Item	Pitch	Mating
Standard	2.00	1215/1220
Alternate		

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
				x.x ±0.40	JYHuang	2012/07/14	UNIT	mm	2243-1XXSXXCUNT1
				x.xx ±0.25	CHECK	DATE	SIZE	A4	TITLE: FH2.00 SINGLE ROW 180° DIP H=4.3
				x.xxx ±0.15	APPROVE	DATE	SHEET	1/1	Customer NO.
				Angle ± 3'			PROJ.		
				DIM TOL					